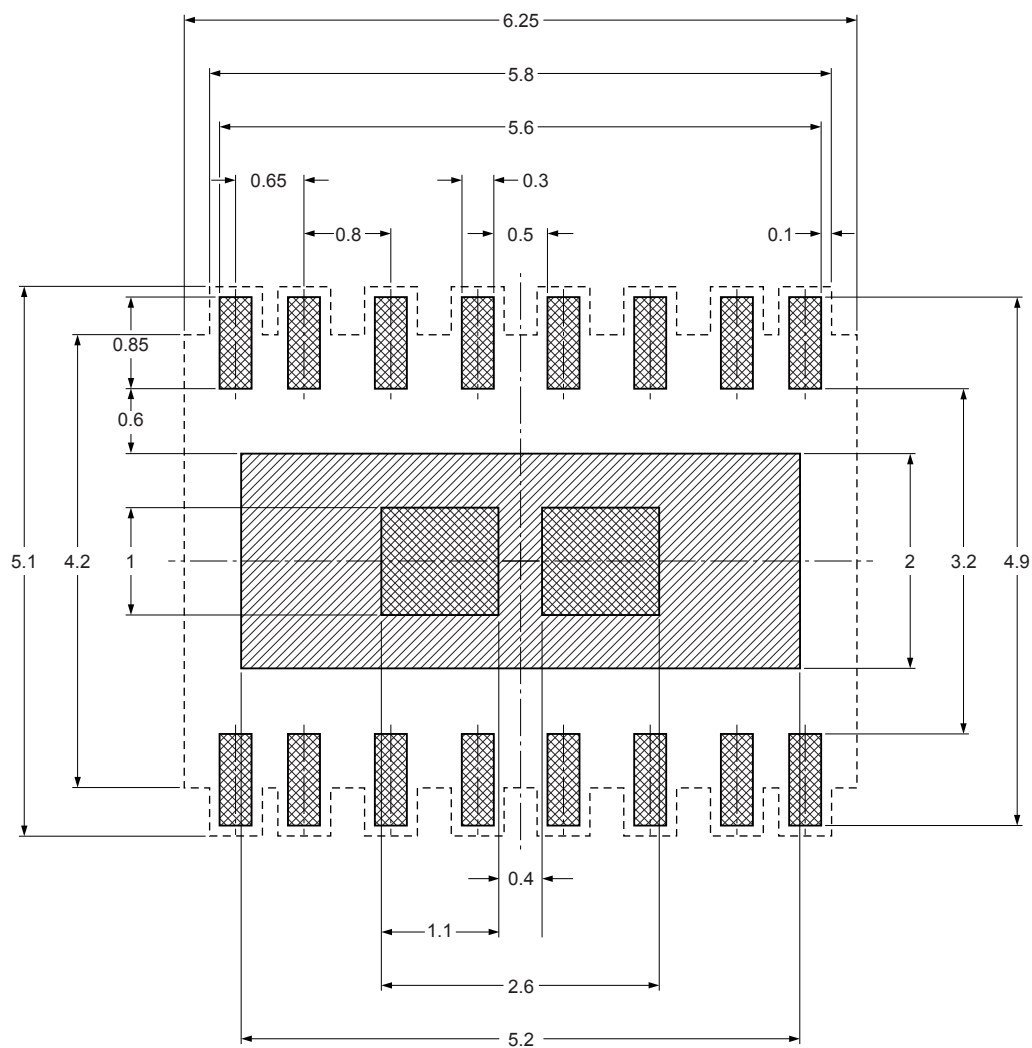






## Footprint information for reflow soldering of HVSON16 (SOT1371-1) package

SOT1371-1



- |   |               |   |                            |
|---|---------------|---|----------------------------|
|  | occupied area |  | solder paste deposit       |
|  | solder lands  |  | solder land + solder paste |

Dimensions in mm

Issue date ~~14-06-25~~  
14-07-03

sot1371-1\_fr